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				Applicati n Number	10/716686	
INF	ORMATION	N DIS	CLOSURE	Filing Date	November 19, 2003	
STATEMENT BY APPLICANT				First Named Inventor	Bert M. VERMEIRE	
				Art Unit Unknown 2829		
(Use as many sheets as necessary)			ecessary)	Examiner Name	Unknown Arleen M. Vazquez	
Sheet	1	of	2	Attorney Docket Number	300-01-1-001	

	NON PATENT LITERATURE DOCUMENTS	
Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
1	V. C. TYREE, "Self stressing test structure cells", Rome Laboratory, Air Force Materiel Command, February 1995, New York.	
2	T. P. MA et al., "Ionizing Radiation Effects in MOS Devices and Circuits", John Wiley and Sons, 1989.	
3	G. ANELLI et al., "Radiation tolerant VLSI circuits in standard deep submicron CMOS technologies for the LHC experiments: Practical design aspects," IEEE Trans. Nucl. Sci., vol. 46, pp. 1690-1696, 1999.	
4	G. S. SHARE, "Effects of Ionizing Radiation on Thin Oxide (20- 1500 Å) MOS Capacitors," J. Appl. Phys., vol. 45, pp. 4894, 1974.	
5	R. C. LACOE et al., "Total-dose radiation tolerance of a commercial 0.35 mm CMOS process," presented at Radiation Effects Data Workshop, 1998.	
6	R. C. LACOE et al., "Total-dose tolerance of a Chartered Semiconductor 0.35 mm CMOS process," presented at Radiation Effects Data Workshop, 1999.	
7	R. C. LACOE et al., "Application of Hardness-By-Design Methodology to Radiation-Tolerant ASIC Technologies," IEEE Trans. Nucl. Sci., vol. 47, pp. 2334-2341, 2000.	
8	R. C. LACOE et al., "Total-dose tolerance of the commercial Taiwan Semiconductor Manufacturing Company (TSMC) 0.35 mm CMOS process," presented at Radiation Effects Data Workshop, 2001.	
9	J. W. R. DAWES et al., "Process technology for radiation-hardened CMOS integrated circuits," IEEE J. Solid State Circuits, vol. SC-11, pp. 459, 1976.	
10	J.M. BENEDETTO et al., "Mosfet and MOS Capacitor Responses to Ionizing Radiation" IEEE Transactions on Nuclear Science, Vol. NS-31, No. 6, December 1984.	
	No.¹ 1 2 3 4 5 6 7 8	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. V. C. TYREE, "Self stressing test structure cells", Rome Laboratory, Air Force Materiel Command, February 1995, New York. T. P. MA et al., "Ionizing Radiation Effects in MOS Devices and Circuits", John Wiley and Sons, 1989. G. ANELLI et al., "Radiation tolerant VLSI circuits in standard deep submicron CMOS technologies for the LHC experiments: Practical design aspects," IEEE Trans. Nucl. Sci., vol. 46, pp. 1690-1696, 1999. G. S. SHARE, "Effects of Ionizing Radiation on Thin Oxide (20- 1500 Å) MOS Capacitors," J. Appl. Phys., vol. 45, pp. 4894, 1974. R. C. LACOE et al., "Total-dose radiation tolerance of a commercial 0.35 mm CMOS process," presented at Radiation Effects Data Workshop, 1998. R. C. LACOE et al., "Total-dose tolerance of a Chartered Semiconductor 0.35 mm CMOS process," presented at Radiation Effects Data Workshop, 1999. R. C. LACOE et al., "Total-dose tolerance of a Chartered Semiconductor 0.35 mm CMOS process," presented at Radiation Effects Data Workshop, 1999. R. C. LACOE et al., "Total-dose tolerance of the commercial Taiwan Semiconductor Manufacturing Company (TSMC) 0.35 mm CMOS process," presented at Radiation-Flects Data Workshop, 2001. J. W. R. DAWES et al., "Process technology for radiation-hardened CMOS integrated circuits," IEEE J. Solid State Circuits, vol. SC-11, pp. 459, 1976. J.M. BENEDETTO et al., "Mosfet and MOS Capacitor Responses to Ionizing

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			Application Number .	10/71	6686		
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STA	STATEMENT BY APPLICANT			First Named Inventor	Bert M. VERMEIRE		
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AV	11	A. MEKKAOUI et al., "30Mrad(SiO2) radiation tolerant pixel front end for the BTEV experiment," Nucl. Instr. and Meth. A, vol. 465, pp. 166-175, 2001.			
AV	12	J. D. M. FLEETWOOD, "A Reevaluation of Worst-Case Post-irradiation Response for Hardened MOS Transistors," IEEE Trans. Nucl. Sci., vol. NS-34, pp. 1178, 1987.			
AV	13	K. P. V. DRESSENDORFER, "The Effects of Test Conditions on MOS Radiation Hardness Results," IEEE Trans. Nucl. Sci., vol. NS-28, pp. 4281, 1981.			
AV	14	M. KIMURA, "Field and Temperature acceleration model for time-dependent dielectric breakdown," IEEE Trans. Electron Devices, vol. 46, pp. 220-229, 1999.			
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